



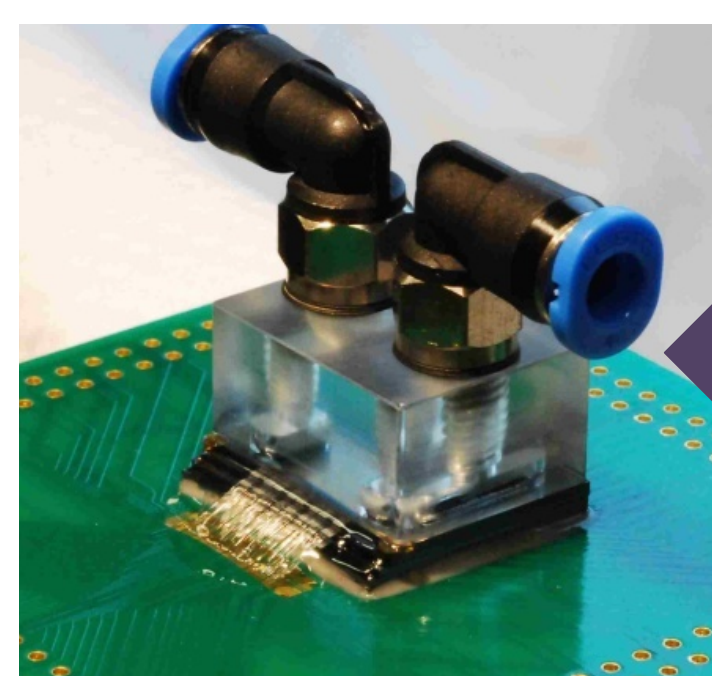
## EDA for CMOSAIC:

### a new generation of CAD tools for liquid-cooled 2D/3D ICs

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EPFL-Embedded Systems Laboratory

Partners: IBM Research  
EPFL-LTCM



#### Our role in CMOSAIC:

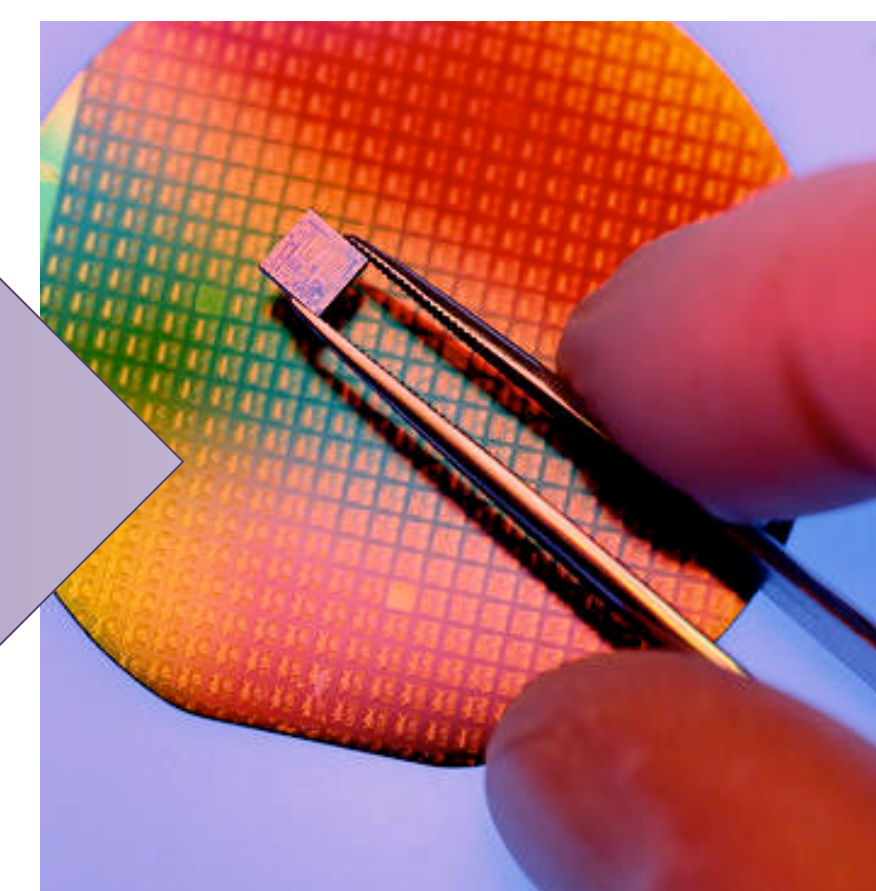
At the Embedded Systems Laboratory, we used our expertise in Electronic Design Automation to develop tools to aid the semiconductor industry in the adoption of liquid and two-phase cooled 2D/3D ICs of the future, and enable their commercially viable mass production.

##### •Simulation

We worked with our partners in IBM Research and LTCM to develop efficient thermal modeling and simulation tools to evaluate designs at early-stage.

##### •Optimization

We also developed design-optimization and run-time thermal management schemes for multi-processor architectures to keep these designs operating in a reliable and energy efficient manner.

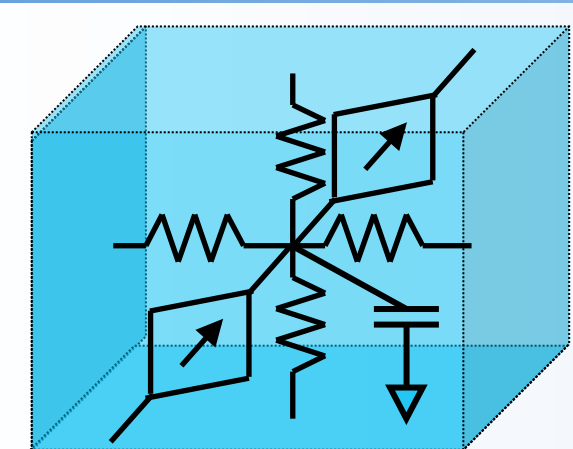


## Simulation

PhD Student: Arvind Sridhar

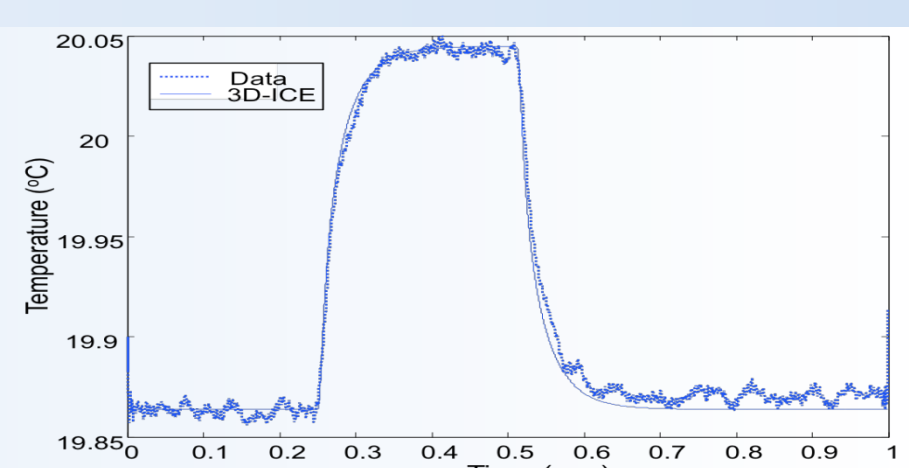


### 3D-ICE: "3D Interlayer Cooling Emulator" 3D



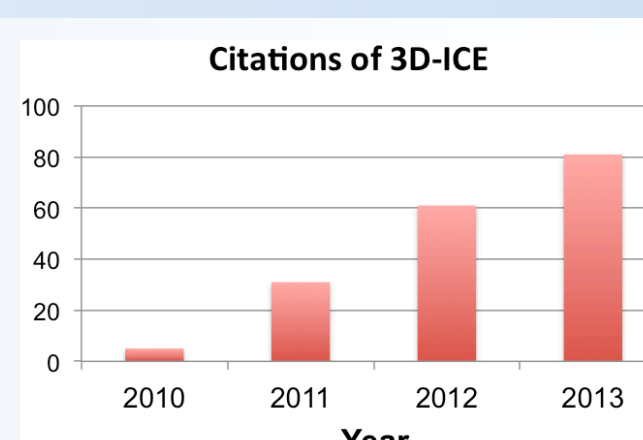
The FIRST Compact Transient Thermal Model for liquid-cooled ICs

Validated against measurements from IBM

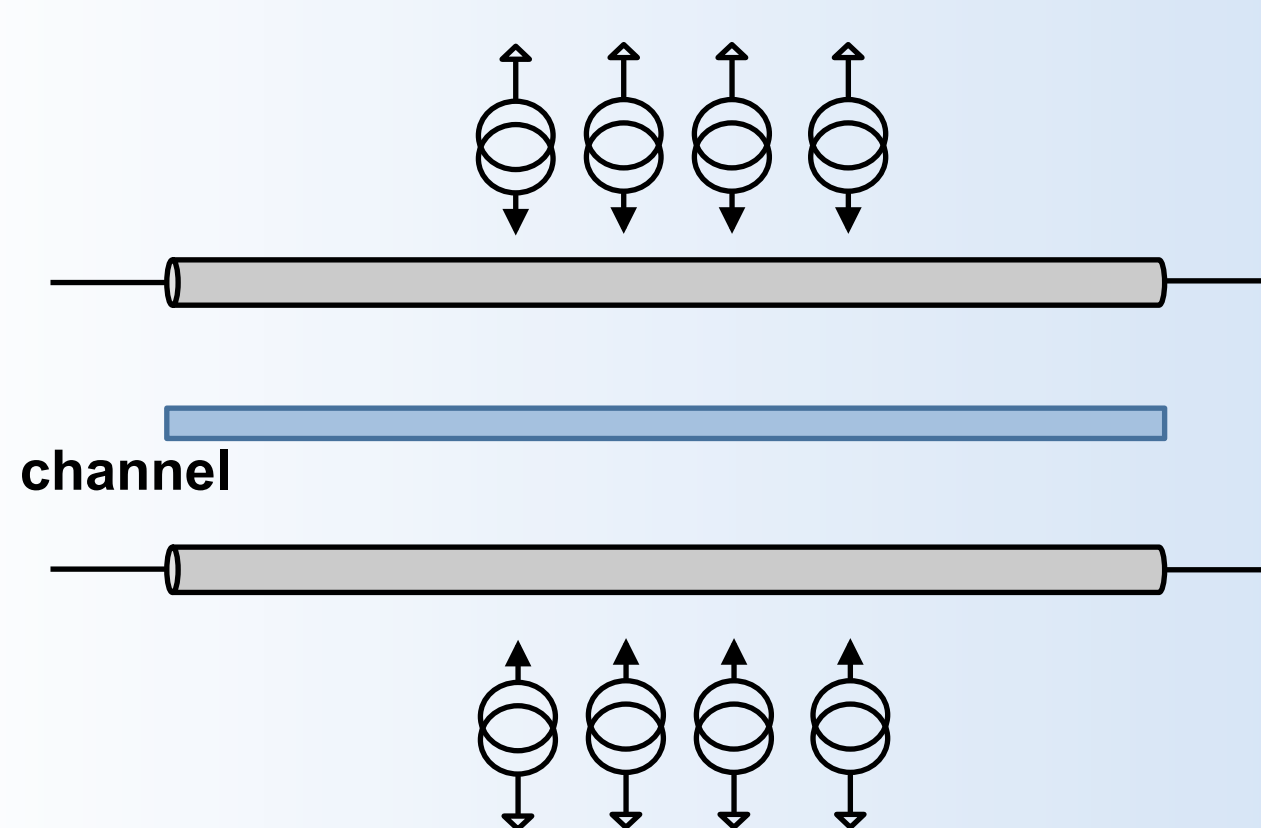


>180 Companies and Universities worldwide use 3D-ICE

3D-ICE cited in >80 conferences and journals



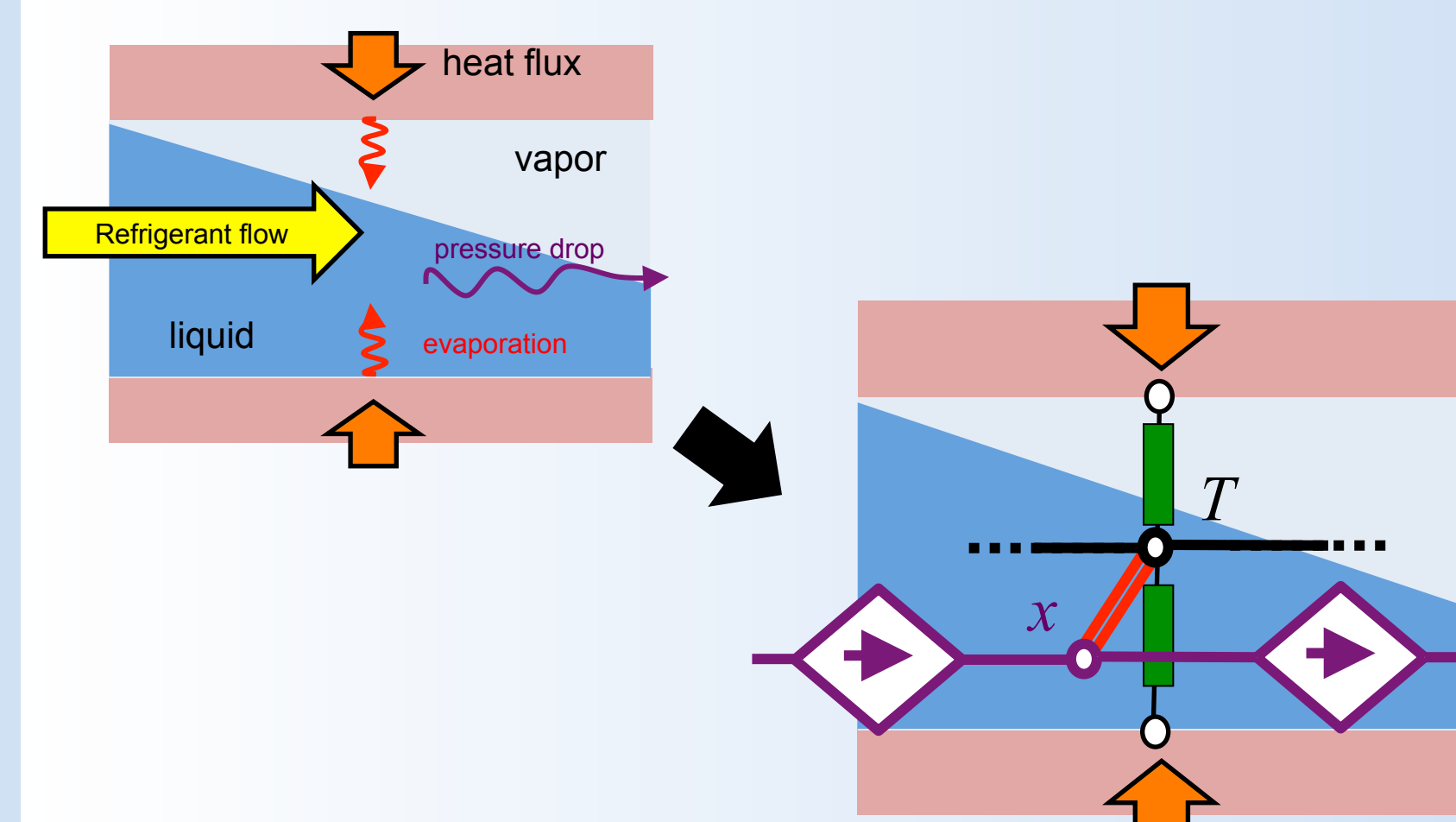
### Semi-analytical model



A new semi-analytical model for liquid-cooled ICs based on transmission-line theory

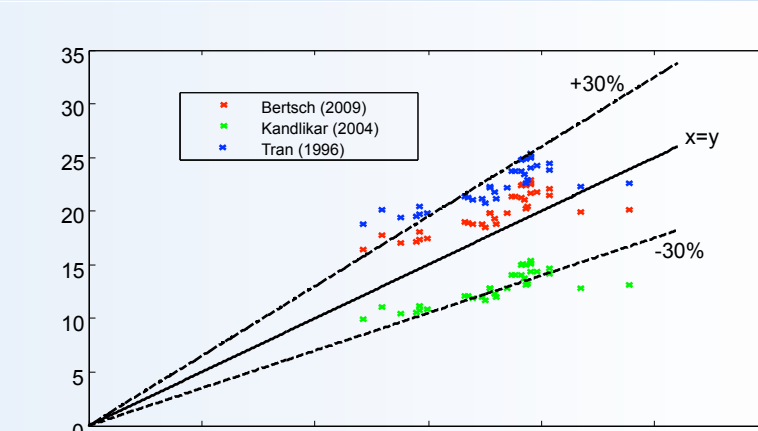
Successfully applied to design-time optimization **GREENCOOL**

### STEAM: Two-phase model



A new compact thermal model for two-phase cooling of ICs

Validated against measurements from LTCM



PhD Student: Mohamed Sabry

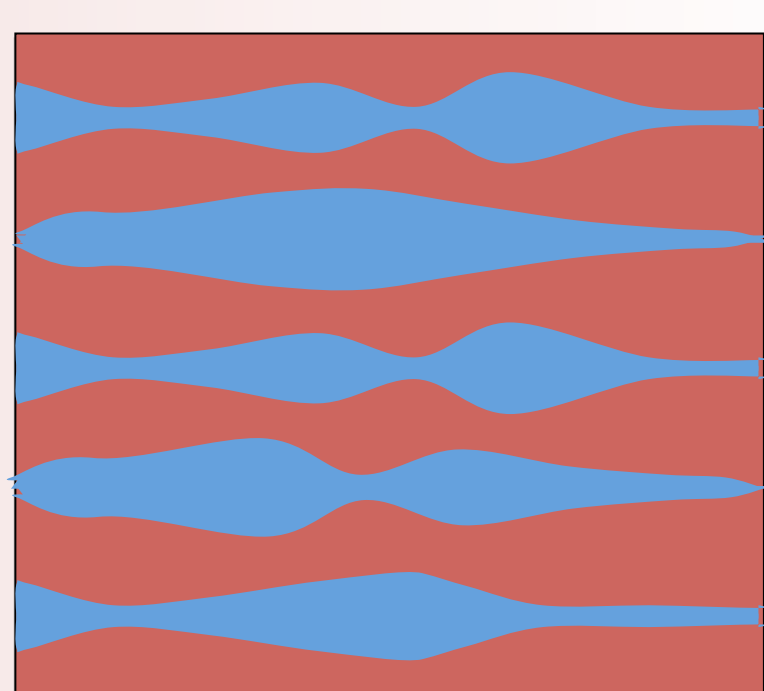
## Optimization

### Design-time optimization using channel modulation **GREENCOOL**

Uniform Width

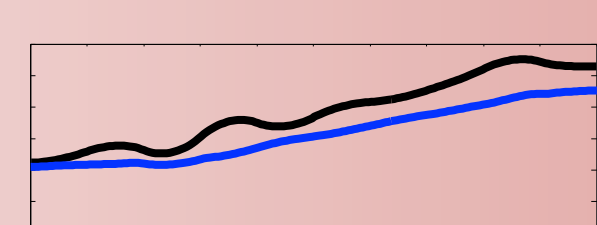


Modulated Width



Customized channel width to meet thermal demands with low cooling power

31% thermal gradient reduction (vs. straight channels)

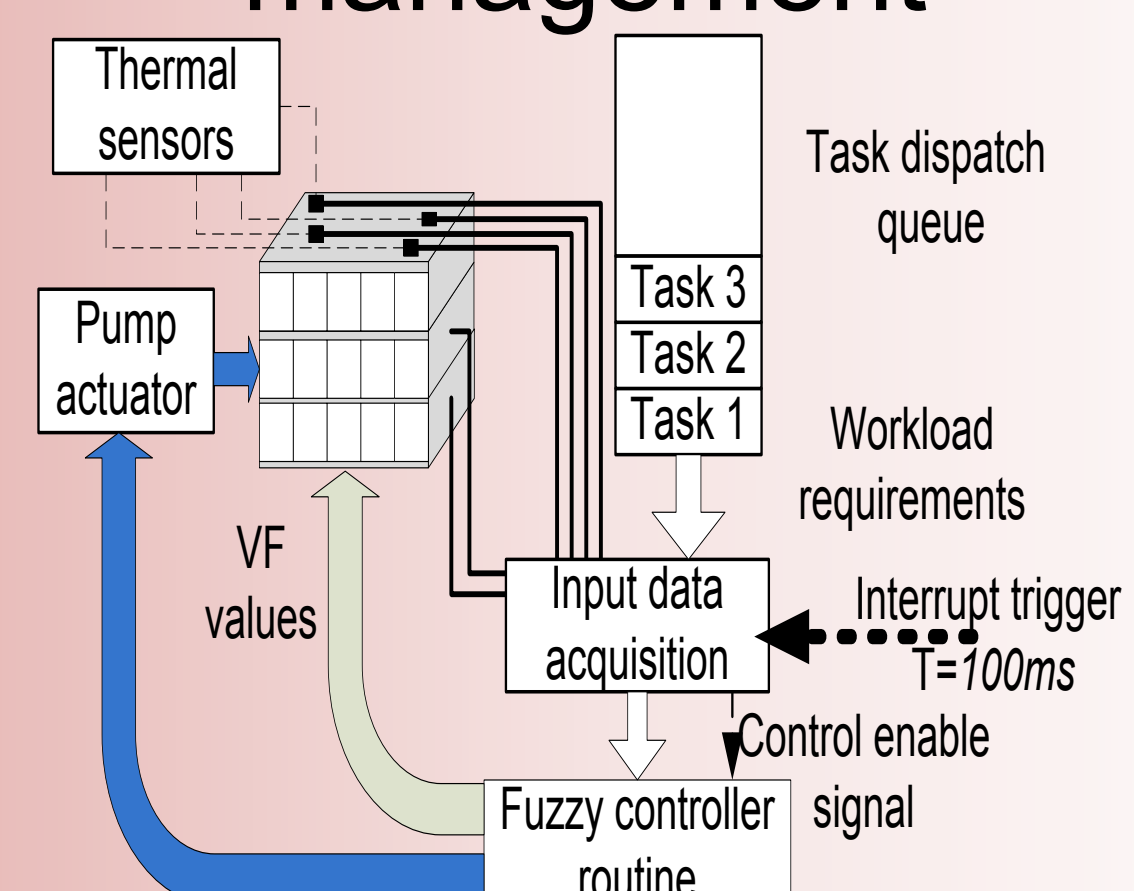


80% cooling power reduction (vs. straight channels)



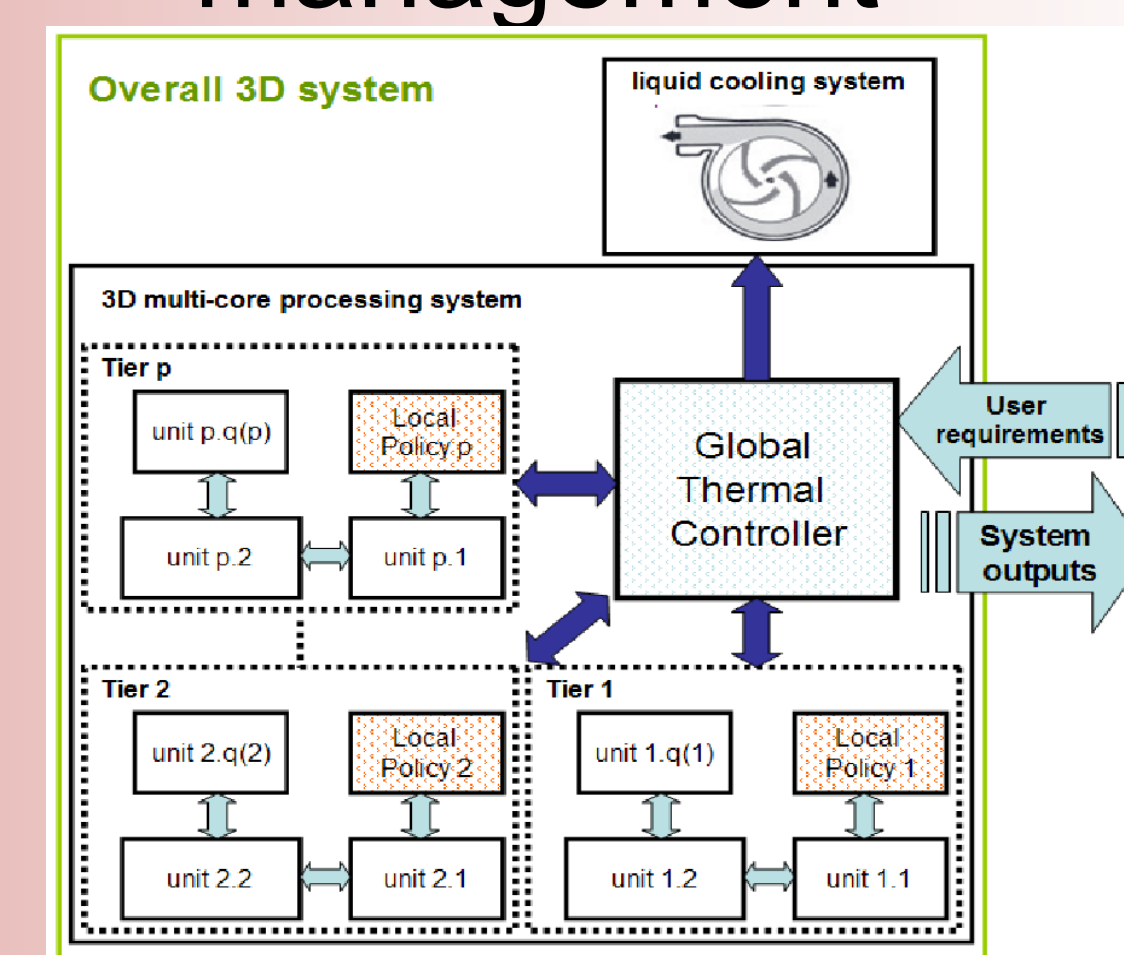
### Run-time thermal management and optimization mechanisms

#### Centralized fuzzy Logic management



Rule-base decisions for flow rate and voltage/frequency tuning

#### Decentralized hierarchical management



Predictive control decisions for flow rate and voltage/frequency tuning

40% cooling and computation power reduction (vs. state of the art)

30% Peak temperature and thermal gradient reduction (vs. state of the art)